IN THE SPECIFICATION:

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~strikethrough~~.

Please AMEND the paragraph beginning at page 19, line 8, as follows:

As shown in Fig. 10, the silicon wafer 23 is then placed on a horizontal plane 35 on a first platen 34 after being reversed to a downward front side position. When the silicon wafer 23 has been reversed, the input/output bumps 19 protrude downward from the surface of the silicon wafer 23. A cylindrical hole or hollow 36 is defined in the first platen 34 so as to allow the downward input/output bumps 19 to enter the hollow 36 when the silicon wafer 23 is placed on the horizontal plane 35 of the first platen 34. The outer periphery of the silicon wafer 23 is received on the horizontal plane 35 around the hollow 36.

Please AMEND the paragraph beginning at page 19, line 18, as follows:

Here, an annular groove 37 (Fig. 10) is defined on the horizontal plane 35 of the first platen 34 so as to surround the hollow 36. The depth *D1* of the annular groove 37 is set equal to the thickness *t2* of the underfill material sheet 29 (see Fig. 6). The annular member 31 is detachably fitted into the annular groove 37. The height measured from the horizontal plane 35 to the first datum plane 32 of the annular member 31 is set equal to the total thickness of the silicon wafer 23 and the resin material sheet 27.

Please AMEND the paragraph beginning at page 20, line 13, as follows:

As shown in Fig. 13, the silicon wafer 23 is then reversed again and placed on a horizontal plane 40 on a second platen 39. The reversal of the silicon wafer 23 can be achieved by grasping or holding the silicon wafer 23. Alternatively, the annular member 31 may be grasped or held in reversing the silicon wafer 23. The silicon wafer 23 is received on the horizontal plane 40 at the backside. As shown in Fig. 14, the second material supplying tape 25 is superposed on the second datum plane 33 of the annular member 31 on the second platen 39 in an upward front side position. The second material supplying tape 25 is then subjected to a heating treatment at the temperature around 70 degrees Celsius. The applied

heat enables softening of the underfill material sheets 29 in the second material supplying tape 25.